



年程科技股份有限公司
TECSTAR TECHNOLOGY CO., LTD.

TB 100505 G300



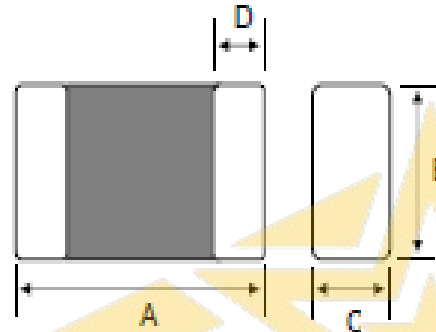
Physical Dimensions : mm (inch)

A = 1.0 ± 0.1 (0.040 \pm 0.004)

B = 0.5 ± 0.1 (0.020 \pm 0.004)

C = 0.5 ± 0.1 (0.020 \pm 0.004)

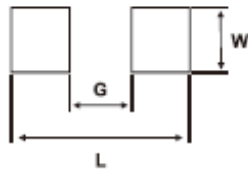
D = 0.25 ± 0.15 (0.010 \pm 0.006)



General Information :

1. Termination Finish is 100% Tin.
2. Components Should be Adequately Preheated Before Soldering.
3. Operating Temperature: -55°C to +125°C
4. Storage Temperature (on Tape & Reel): 40°C MAX. , 70% RH

Land Patterns for Reflow Soldering



L	W	G
2.20(0.086)	0.70(0.028)	0.40(0.016)

Packing Method:

One reel = 10,000 pcs

One Box = 500,000 pcs

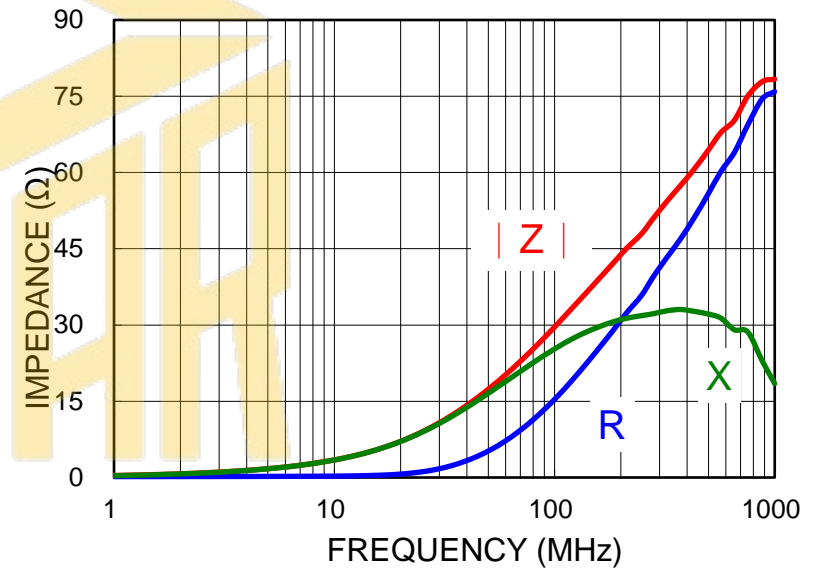
One Box = 8.4 KG

Electrical Characteristics :

	Value	Unit	Tolerance	Test Condition
Impedance	30	Ω	$\pm 25\%$	100MHz / 100mV
DCR	0.30	Ω	Max.	
IDC	500	mA	Max.	

Typical Impedance Characteristics : HP 4291B

TB100505G300



				Multilayer Ferrite Chip Beads	
				P/N	TB 100505 G300
N000	Initial			Version	N000
VER.	DESCRIPTION	DATE	BY		



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